



Product Change Notification: ALAN-08XQQK189

Date:

06-Dec-2024

Product Category:

16-Bit - Microcontrollers And Digital Signal Controllers, 32-Bit Microcontrollers, 8-Bit Microcontrollers

Notification Subject:

CCB 7116 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material and QMI519 as an additional die attach material for selected DSPIC33xx, PIC24EPxx, PIC32MXxx, PIC24FJxx, and PIC18F9xx device families available in 100L TQFP (12x12x1mm) package at MTAI assembly site.

Affected CPNs:

[ALAN-08XQQK189_Affected_CPN_12062024.pdf](#)

[ALAN-08XQQK189_Affected_CPN_12062024.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material and QMI519 as an additional die attach material for selected DSPIC33xx, PIC24EPxx, PIC32MXxx, PIC24FJxx, and PIC18F9xx device families available in 100L TQFP (12x12x1mm) package at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)

Wire Material	Au	Au	CuPdAu
Die Attach Material	3280	3280	QMI519
Molding Compound Material	G700HA	G700HA	G700HA
Lead-Frame Material	C7025	C7025	C7025

*CPNs with Au as an existing wire material

	Pre Change	Post Change	
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)
Wire Material	CuPdAu	CuPdAu	CuPdAu
Die Attach Material	3280	3280	QMI519
Molding Compound Material	G700HA	G700HA	G700HA
Lead-Frame Material	C7025	C7025	C7025

*CPNs with CuPdAu as an existing wire material

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as an additional bond wire material and QMI519 as an additional die attach material.

Change Implementation Status: In Progress

Estimated First Ship Date: 15 January 2025 (date code: 253)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	September 2024					>	December 2024					January 2025				
Work Week	36	37	38	39	40		49	50	51	52	53	01	02	03	04	05
Initial PCN Issue Date			X													
Qual Report Availability							X									
Final PCN Issue Date							X									
Estimated Implementation Date														X		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: September 17, 2024: Issued initial notification.
December 06, 2024: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on January 15, 2025.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_ALAN-08XQQK189_Qual Report.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this

notification.

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Affected Catalog Part Numbers (CPN)

PIC32MX775F256LT-80I/PT
PIC32MX775F256LT-80V/PT
PIC32MX775F512L-80I/PT
PIC32MX775F512L-80V/PT
PIC32MX775F512LT-80I/PT
PIC32MX775F512LT-80V/PT
PIC32MX795F512L-80I/PT
PIC32MX795F512L-80I/PTE22
PIC32MX795F512L-80V/PT
PIC32MX795F512LT-80I/PT
PIC32MX795F512LT-80I/PTE21
PIC32MX795F512LT-80I/PTE22
PIC32MX795F512LT-80V/PT
PIC32MX170F512L-50I/PT
PIC32MX170F512L-I/PT
PIC32MX170F512LT-50I/PT
PIC32MX170F512LT-I/PT
PIC32MX170F512LT-V/PT
PIC32MX170F512L-V/PT
PIC32MX230F128L-50I/PT
PIC32MX230F128L-I/PT
PIC32MX230F128LT-50I/PT
PIC32MX230F128LT-I/PT
PIC32MX230F128LT-V/PT
PIC32MX230F128L-V/PT
PIC32MX250F256L-50I/PT
PIC32MX250F256L-I/PT
PIC32MX250F256LT-50I/PT
PIC32MX250F256LT-I/PT
PIC32MX250F256LT-V/PT
PIC32MX250F256L-V/PT
PIC32MX270F512L-50I/PT
PIC32MX270F512L-I/PT
PIC32MX270F512LT-50I/PT
PIC32MX270F512LT-I/PT
PIC32MX270F512LT-V/PT
PIC32MX270F512L-V/PT
PIC32MX330F064L-I/PT
PIC32MX330F064LT-I/PT
PIC32MX330F064LT-V/PT
PIC32MX330F064L-V/PT
PIC32MX350F128L-I/PT
PIC32MX350F128LT-I/PT
PIC32MX350F128LT-V/PT
PIC32MX350F128L-V/PT
PIC32MX350F256L-I/PT

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PIC32MX350F256LT-V/PT
PIC32MX350F256L-V/PT
PIC32MX370F512L-I/PT
PIC32MX370F512LT-I/PT
PIC32MX370F512LT-V/PT
PIC32MX370F512L-V/PT
PIC32MX430F064L-I/PT
PIC32MX430F064LT-I/PT
PIC32MX430F064LT-V/PT
PIC32MX430F064L-V/PT
PIC32MX450F128L-I/PT
PIC32MX450F128LT-I/PT
PIC32MX450F128LT-V/PT
PIC32MX450F128L-V/PT
PIC32MX450F256L-120/PT
PIC32MX450F256L-I/PT
PIC32MX450F256LT-120/PT
PIC32MX450F256LT-I/PT
PIC32MX450F256LT-V/PT
PIC32MX450F256L-V/PT
PIC32MX470F512L-120/PT
PIC32MX470F512L-120/PT021
PIC32MX470F512L-I/PT
PIC32MX470F512LT-120/PT
PIC32MX470F512LT-120/PT022
PIC32MX470F512LT-I/PT
PIC32MX470F512LT-I/PT021
PIC32MX470F512LT-I/PT022
PIC32MX470F512LT-V/PT
PIC32MX470F512L-V/PT
DSPIC33EP128GM310-I/PT
DSPIC33EP128GM710-E/PT
DSPIC33EP128GM710-I/PT
DSPIC33EP256GM310-I/PT
DSPIC33EP256GM310T-I/PT
DSPIC33EP256GM710-E/PT
DSPIC33EP256GM710-I/PT
DSPIC33EP256GM710T-I/PT
DSPIC33EP256MU810-E/PT
DSPIC33EP256MU810-I/PT
DSPIC33EP256MU810T-E/PT
DSPIC33EP256MU810T-I/PT
DSPIC33EP256MU810T-I/PTC02
DSPIC33EP512GM310-I/PT
DSPIC33EP512GM310T-I/PT
DSPIC33EP512GM710-E/PT
DSPIC33EP512GM710-H/PT
DSPIC33EP512GM710-I/PT

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DSPIC33EP512MU810-I/PT
DSPIC33EP512MU810T-E/PT
DSPIC33EP512MU810T-I/PT
PIC18F95J94-I/PT
PIC18F95J94T-I/PT
PIC18F96J94-I/PT
PIC18F97J94-I/PT
PIC18F97J94T-I/PT
PIC24EP256GU810-E/PT
PIC24EP256GU810-I/PT
PIC24EP256GU810T-E/PT
PIC24EP256GU810T-I/PT
PIC24EP512GU810-E/PT
PIC24EP512GU810-I/PT
PIC24EP512GU810T-E/PT
PIC24EP512GU810T-I/PT
PIC24FJ128DA110-I/PT
PIC24FJ128DA210-I/PT
PIC24FJ128GA310-I/PT
PIC24FJ128GA310-I/PTC04
PIC24FJ128GA310-I/PTREL
PIC24FJ128GA310T-I/PT
PIC24FJ128GA410-I/PT
PIC24FJ128GA410T-I/PT
PIC24FJ128GB210-I/PT
PIC24FJ128GB410-I/PT
PIC24FJ128GB410T-I/PT
PIC24FJ128GC010-I/PT
PIC24FJ128GC010T-I/PT
PIC24FJ256DA110-I/PT
PIC24FJ256DA210-I/PT
PIC24FJ256DA210-I/PTREL
PIC24FJ256DA210T-I/PT
PIC24FJ256GA410-I/PT
PIC24FJ256GA410T-I/PT
PIC24FJ256GB210-I/PT
PIC24FJ256GB210T-I/PT
PIC24FJ256GB410-I/PT
PIC24FJ256GB410T-I/PT
PIC24FJ64GA310-I/PT
PIC24FJ64GA310-I/PTREL
PIC24FJ64GA310T-I/PT
PIC24FJ64GA410-I/PT
PIC24FJ64GA410T-I/PT
PIC24FJ64GB410-I/PT
PIC24FJ64GB410T-I/PT
PIC24FJ64GC010-I/PT
PIC32MX130F128L-50I/PT

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PIC32MX130F128LT-50I/PT
PIC32MX130F128LT-I/PT
PIC32MX130F128LT-V/PT
PIC32MX130F128L-V/PT
PIC32MX150F256L-50I/PT
PIC32MX150F256L-I/PT
PIC32MX150F256LT-50I/PT
PIC32MX150F256LT-I/PT
PIC32MX150F256LT-V/PT
PIC32MX150F256L-V/PT
PIC32MX575F512L-80V/PTC22
PIC32MX575F512LT-80I/PT
PIC32MX575F512LT-80I/PT024
PIC32MX575F512LT-80I/PT025
PIC32MX575F512LT-80V/PT
PIC32MX575F512LT-80V/PTC22
PIC32MX664F064L-I/PT
PIC32MX664F064LT-I/PT
PIC32MX664F064LT-V/PT
PIC32MX664F064L-V/PT
PIC32MX664F128L-I/PT
PIC32MX664F128LT-I/PT
PIC32MX664F128LT-V/PT
PIC32MX664F128L-V/PT
PIC32MX675F256L-80I/PT
PIC32MX675F256L-80V/PT
PIC32MX675F256LT-80I/PT
PIC32MX675F256LT-80V/PT
PIC32MX675F512L-80I/PT
PIC32MX675F512L-80V/PT
PIC32MX675F512LT-80I/PT
PIC32MX675F512LT-80V/PT
PIC32MX695F512L-80I/PT
PIC32MX695F512L-80I/PT020
PIC32MX695F512L-80I/PT021
PIC32MX695F512L-80I/PT023
PIC32MX695F512L-80I/PTD21
PIC32MX695F512L-80I/PTD22
PIC32MX695F512L-80V/PT
PIC32MX695F512LT-80I/PT
PIC32MX695F512LT-80I/PTD21
PIC32MX695F512LT-80I/PTD22
PIC32MX695F512LT-80V/PT
PIC32MX764F128L-I/PT
PIC32MX764F128LT-I/PT
PIC32MX764F128LT-V/PT
PIC32MX764F128L-V/PT
PIC32MX775F256L-80I/PT

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PIC32MX530F128L-50I/PT
PIC32MX530F128L-I/PT
PIC32MX530F128LT-50I/PT
PIC32MX530F128LT-I/PT
PIC32MX530F128LT-V/PT
PIC32MX530F128L-V/PT
PIC32MX534F064L-I/PT
PIC32MX534F064LT-I/PT
PIC32MX534F064LT-V/PT
PIC32MX534F064L-V/PT
PIC32MX550F256L-50I/PT
PIC32MX550F256L-I/PT
PIC32MX550F256LT-50I/PT
PIC32MX550F256LT-I/PT
PIC32MX550F256LT-V/PT
PIC32MX550F256L-V/PT
PIC32MX564F064L-I/PT
PIC32MX564F064LT-I/PT
PIC32MX564F064LT-V/PT
PIC32MX564F064L-V/PT
PIC32MX564F128L-I/PT
PIC32MX564F128LT-I/PT
PIC32MX564F128LT-V/PT
PIC32MX564F128L-V/PT
PIC32MX570F512L-50I/PT
PIC32MX570F512L-I/PT
PIC32MX570F512LT-50I/PT
PIC32MX570F512LT-I/PT
PIC32MX570F512LT-V/PT
PIC32MX570F512L-V/PT
PIC32MX575F256L-80I/PT
PIC32MX575F256L-80V/PT
PIC32MX575F256LT-80I/PT
PIC32MX575F256LT-80V/PT
PIC32MX575F512L-80I/PT
PIC32MX575F512L-80I/PT024
PIC32MX575F512L-80I/PT025
PIC32MX575F512L-80I/PTC21
PIC32MX575F512L-80V/PT